



DATE: 11 May, 2023

PCN #: 2628

PCN Title: Qualification of Additional Wafer Solderable Front Metal Plating,
Back Grinding and Back Metal Process Source for Select Discrete Products

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request immediately. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



PRODUCT CHANGE NOTICE**PCN-2628 REV 1**

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
11 May, 2023	11 August, 2023	Discrete Semiconductor	Additional Solderable Front Metal Plating, Back Grinding and Back Metal Process Source	2628
TITLE				
Qualification of Additional Wafer Solderable Front Metal Plating, Back Grinding and Back Metal Process Source for Select Discrete Products				
DESCRIPTION OF CHANGE				
<p>This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes Incorporated has qualified internal "Diodes Technology (Cheng Du) Company Limited" (CAT) located in Chengdu, China as an additional wafer solderable front metal plating and back grinding and back metal process facility for select products listed below.</p> <p>Full electrical characterization and high reliability testing has been completed on representative part numbers to ensure no change to device functionality or electrical specifications in the datasheet. Refer to the attached qualification report embedded in this file (to view, download this PCN file then open it with a PDF viewer to see the attached qual report).</p> <p>There will be no change to the Form, Fit, or Function of affected products.</p>				
IMPACT				
No change in datasheet parameters and product performance.				
PRODUCTS AFFECTED				
Table 1 – Add CAT as additional wafer solderable front metal plating and back grinding and back metal process facility				
WEB LINKS				
Manufacturer's Notice:	https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/			
For More Information Contact:	https://www.diodes.com/about/contact-us/contact-sales/			
Data Sheet:	https://www.diodes.com/catalog/			
DISCLAIMER				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				



Table 1 – Add CAT as the additional wafer solderable front metal plating and back grinding and back metal process facility

DMN22M5UFG-7	DMP2004UFG-13	DMT10H015LFG-13	DMT32M5LFG-13	DMT8008LFG-7	DMTH6002LPS-13
DMN3012LEG-13	DMP2004UFG-7	DMT10H015LFG-7	DMT32M5LFG-7	DMTH10H003SPSW-13	DMTH6005LFG-13
DMN3012LEG-7	DMP2005UFG-13	DMT10H017LPD-13	DMT4002LPS-13	DMTH3002LPS-13	DMTH6005LFG-7
DMN3013LDG-13	DMP2005UFG-7	DMT3002LPS-13	DMT6002LPS-13	DMTH41M8SPS-13	DMTH61M5SPSW-13
DMN3013LFG-7	DMP3007SFG-13	DMT3003LFG-13	DMT6005LFG-13	DMTH43M8LFG-13	DMTH62M8LPS-13
DMN3022LDG-13	DMP3007SFG-7	DMT3003LFG-7	DMT6005LFG-7	DMTH43M8LFG-7	DMTH62M8SPS-13
DMN3022LDG-7	DMP32M6SPS-13	DMT31M6LPS-13	DMT6007LFG-13	DMTH45M5LPDW-13	DMTH8003SPS-13
DMN3022LFG-13	DMT10H003SPSW-13	DMT32M4LFG-13	DMT6007LFG-7	DMTH45M5LPSW-13	DMTH8008LFG-7
DMN3022LFG-7	DMT10H009LFG-13	DMT32M4LFG-7	DMT61M5SPSW-13	DMTH45M5SPDW-13	DMTH8008SFG-7
DMP2002UPS-13	DMT10H009LFG-7	DMT32M4LPSW-13	DMT8008LFG-13	DMTH45M5SPSW-13	